

# JIS

**JAPANESE INDUSTRIAL STANDARD**

**Single and double sided  
printed wiring boards**

**JIS C 5013—1996**

**Translated and Published**

**by**

**Japanese Standards Association**

**In the event of any doubt arising,  
the original Standard in Japanese is to be final authority**

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Single and double sided printed wiring boards

C 5013-1996

1. Scope This Japanese Industrial Standard specifies single and double sided printed wiring boards mainly used for electronic equipment (hereafter referred to as "printed boards"). However, this Standard is not applicable for flexible printed wiring boards, flex-rigid printed wiring boards and metal core printed wiring boards.

Remarks 1. The following Standards are cited in this Standard :

- JIS C 5001 General rules for electronic components
- JIS C 5012 Test methods for printed wiring boards
- JIS C 5603 Terms and definitions for printed circuits
- JIS C 6482 Copper-clad laminates for printed wiring boards – Paper base, epoxy resin
- JIS C 6484 Copper-clad laminates for printed wiring boards – Glass fabric base, epoxy resin
- JIS C 6485 Copper-clad laminates for printed wiring boards – Paper base, phenolic resin
- JIS C 6488 Copper-clad laminates for printed wiring boards – Glass cloth surfaces, cellulose paper core, epoxy resin
- JIS C 6489 Copper-clad laminates for printed wiring boards – Glass cloth surfaces, nonwoven glass core, epoxy resin
- JIS C 6490 Copper-clad laminates for printed wiring boards – Glass fabric base, modified and unmodified polyimide resin
- JIS C 6492 Copper-clad laminates for printed wiring boards – Glass fabric base, Bismaleimide/Triazine/Epoxide

2. The International Standards corresponding to this Standard are given below.

- IEC 326-3 (1991) Printed boards. Part 3: Design and use of printed boards
- IEC 326-4 (1980) Printed boards. Part 4: Specification for single and double sided printed boards with plain holes
- IEC 326-5 (1980) Printed boards. Part 5: Specification for single and double sided printed boards with plated-through holes

2. Definitions For the purpose of this standard, in addition to the definitions specified in JIS C 5001, and JIS C 5603, the following principal definitions apply.

- (1) external dimensions This means specified shape and dimensions of printed board.
- (2) sub-reference hole The elongated circular hole intended to support the function of the reference hole, used for the adjustment of longitudinal errors.